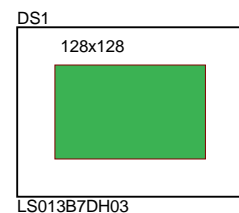
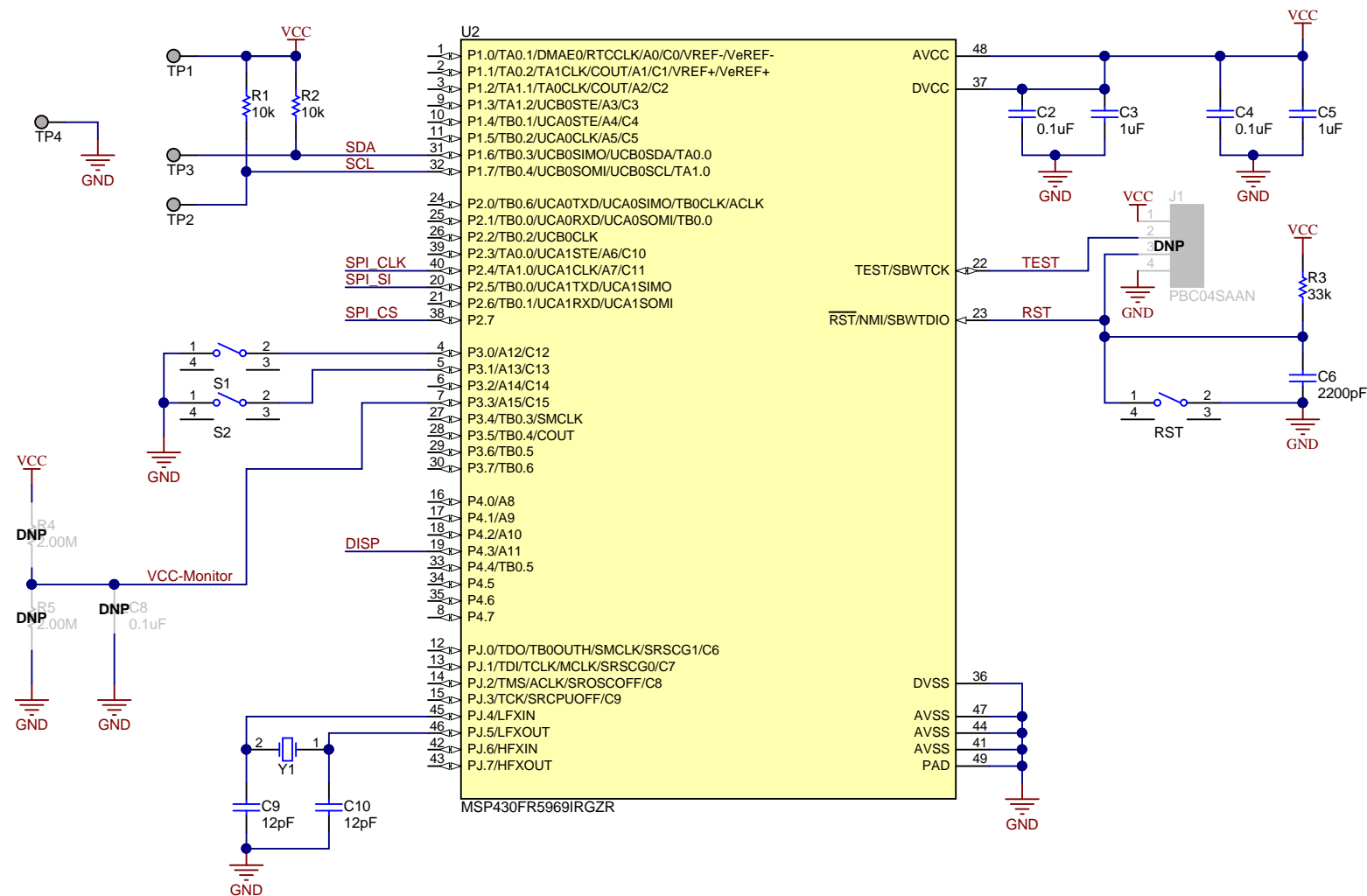
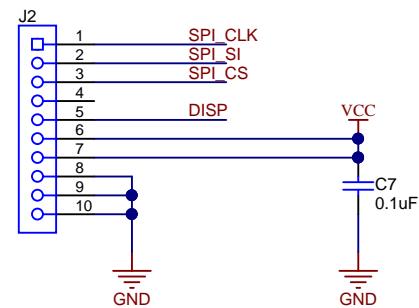


FET protects against reverse polarity without shorting battery



LS013B7DH03



Orderable: HDC2010METER-EVM	Designed for: Public Release	Mod. Date: 4/30/2018
TID #: TIDA-01625	Project Title: HDC2010METER-EVM	
Number: SENS020	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: SENS020_SCH.SchDoc	Size: B
Engineer: Ren Schackmann	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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PCB Number: SENS020  
PCB Rev: A

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WEEE logo



ZZ1  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4  
**Label Assembly Note**  
These assemblies must not be washed after the HDC device is mounted.

ZZ5  
**Label Assembly Note**  
These assemblies must not have flux contamination between the HDC device and the PCB.

ZZ6  
**Label Assembly Note**  
Recommended to assemble and wash top side components before assembling HDC on bottom side.

Orderable: <a href="#">HDC2010METER-EVM</a>	Designed for: <a href="#">Public Release</a>	Mod. Date: 1/22/2018	<p>TEXAS INSTRUMENTS <a href="http://www.ti.com">http://www.ti.com</a> © Texas Instruments 2017</p>
TID #: <a href="#">TIDA-01625</a>	Project Title: <a href="#">HDC2010METER-EVM</a>		
Number: <a href="#">SENS020</a>	Rev: <a href="#">A</a>	Sheet Title:	
SVN Rev: <a href="#">Version control disabled</a>	Assembly Variant: <a href="#">001</a>	Sheet: <a href="#">3</a> of <a href="#">3</a>	
Drawn By: <a href="#">Ren Schackmann</a>	File: <a href="#">SENS020_Hardware.SchDoc</a>	Size: B	
Engineer: <a href="#">Ren Schackmann</a>	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		

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